



### 3. DIELECTRIC PASTES

#### 3.1 LOW TEMPERATURE OVERGLAZE

	I-4337	I-4337C	I-4347	I-4347C	I-4350
<b>Viscosity</b> HBT SC4-14 25 °C 10 rpm	80~150Kcps				
<b>Color</b>	Light Green	White	Light Green	White	Blue
<b>Print Screen Mech</b>	200~325mesh				
<b>Drying</b>	100~125°C、10~15min				
<b>Firing</b>	520~530°C、(Peak)5min		500°C、(Peak)5min		520~530°C
<b>Fired Thickness (um)</b>	8~12µ m				
<b>Thinner</b>	V-100				

#### 3.2 OVERGLAZE FOR CHIP RESISTOR

	(Test Method)	I-4311	I-4321	I-4322	I-4323
<b>Specific Gravity</b>		2.8	2.2	2.2	1.6
<b>Viscosity (Kcps)</b>	HBT SC4-14 25 °C 10rpm	80~150	120~200	120~200	250~400
<b>Color</b>		Light Green	Black	Green	White
<b>Acid Resistant</b>	5% H <sub>2</sub> SO <sub>4</sub> 30min	Good			
<b>Print Screen Mech (Mesh)</b>	Stainless Steel	200~250	200~250	200~250	325
<b>Screen Thickness (µm)</b>		70	115	115	60
<b>Drying</b>		100~150°C, 10~15min			
<b>Firing</b>		600°C, (Peak)5min			
<b>Fired Thickness (µm)</b>		8~12	10~15	10~15	8~12
<b>Thinner</b>		V-100			

#### 3.3 DIELECTRIC PASTES

Product	I-4385	I-4389
<b>Color</b>	Blue	Blue
<b>Viscosity (Kcps)</b>	150~250	100~200
<b>Dielectric Constant</b>	9~15	9~15
<b>Breakdown Voltage (V)</b>	>400	>400
<b>Insulation Resistance ( ohm )</b>	>10 <sup>12</sup>	>10 <sup>12</sup>
<b>Dissipation Factor (%)</b>	<1	<1
<b>Fired(°C)</b>	850	850
<b>Fired Thickness( µ m)</b>	>40	>40
<b>Use</b>	(Multi-layer crossover)	(Stainless steel substrates)